

### Abstract of the Disclosure

An integrated circuit cover incorporating a spring portion is described. The spring portion may include any structure that allows displacement between a plate portion  
5 of the integrated circuit cover and an attachment portion of the integrated circuit cover and that provides a substantially equalizing effect of pressure on the plate portion. The spring portion is preferably more flexible than the plate portion. The integrated circuit cover accommodates variations in the mounted height of integrated circuits over which the integrated circuit cover is installed. The integrated circuit cover may be formed as a  
10 unitary structure or may be constructed as an assembly of multiple components.